

BB02-GK :- 2.00mm x 2.00mm (0.079" x 0.079") SIDE ENTRY FEMALE HEADER, DUAL ROW, BOARD TO BOARD - 04 TO 50 CONTACTS

SPECIFICATIONS

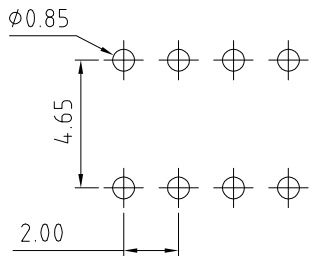
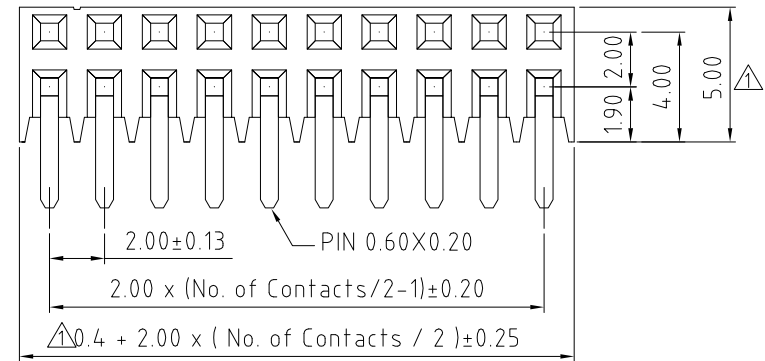
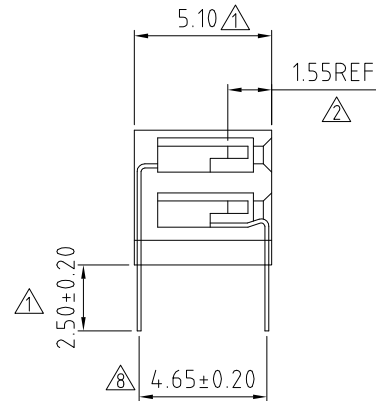
CURRENT RATING	2 AMP
INSULATOR RESISTANCE	1000 MEGOHMS MIN.
DIELECTRIC WITHSTANDING	AC 500 V
OPERATING TEMPERATURE	-40°C TO +105°C
CONTACT MATERIAL	PHOSPHOR BRONZE
INSULATOR MATERIAL	THERMOPLASTIC, UL 94V-0
	STANDARD: NYLON 6T
PLATING	GOLD OR TIN OVER 30~50U" NICKEL
SOLDERABILITY	IR REFLOW: 260°C FOR 10 SEC
	WAVE: 230°C FOR 5-10 SEC
	MANUAL SOLDER: 350°C FOR 3-5 SEC

NOTES:

1. PACKED IN TUBE OR BOX (SMALL PIN NUMBERS).
2. RECOMMENDED MATING PIN LENGTH: 4.0MM. \triangle

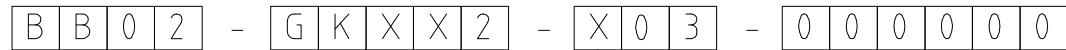
MATES WITH :-

BB02-FA	BB02-FT	BB02-4F
BB02-FD	BB02-FU	
BB02-FE	BB02-FZ	
BB02-FG	BB02-RH	
BB02-FR	BB02-RN	



RECOMMENDED PC BOARD HOLE LAYOUT
(TOLERANCE: ±0.05)

HOW TO ORDER



NO. OF CONTACTS: \triangle 04 TO 50

CONTACT PLATING OPTIONS: \triangle
 K = GOLD FLASH (STANDARD)
 A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL
 B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL
 C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL
 T = BRIGHT TIN
 M = MATT TIN

REV.	DATE & DRN
11	05/26/02 - S11 RELEASE
12	08/07/02 - CHC DRAWING MODIFICATION
13	09/07/06 - CHC AMEND NO. OF CONTACTS
14	09/07/06 - CHC DRAWING MODIFICATION
15	09/08/06 - NYW ADD CONTACT POINT DIM
16	09/08/06 - NYW DRAWING MODIFICATION
17	09/08/06 - NYW ADD NOTES 2
18	09/08/06 - CHC PLATING MODIFICATION
19	09/08/06 - CHC REMOVE SELECTIVE GOLD CONTACT PLATING
20	09/08/06 - CHC PLATING MODIFICATION
21	09/08/06 - CHC DRAWING MODIFICATION
22	09/08/06 - NYW FOOTPRINT AMENDMENT
23	09/08/06 - NYW AMEND NOTE 1

Scale:	5:1
Drawn:	CHC
App'd:	XXXX
Date:	30 OCT. '13
THIRD ANGLE	
Title	SOCKET
Revision:	19

Unstated Tolerances:	Material
X ± 0.30	SEE NOTE
X ± 0.25	
XX ± 0.15	
XXX ± 0.10	
	NOT TO SCALE
	Unit: mm

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Type:	BB02-GK
Drawing Number:	BB02-GK
Sheet	1 of 1
Drawing	© E and O E